#### **Examination 2020 under cluster 4 (PCE)**

Program: BE Electronics and Telecommunication Engineering Curriculum Scheme: Rev2012 Examination: Third Year Semester VI Course Code: ETC606 and Course Name: \_VLSI Design\_\_\_

Time: 1 hour

Max. Marks: 50

\_\_\_\_\_

Note to the students:- All the Questions are compulsory and carry equal marks .

Q1.	The is used to reduce the resistivity of poly silicon.			
Option A:	Photo resist			
Option B:	Etching			
Option C:	Doping impurities			
Option D:	Oxidation			
Q2.	To grow the polysilicon gate layer, which of the following chemical is used for			
	chemical vapour deposition?			
Option A:	Silicon Nitride(Si3N4)			
Option B:	Silane gas(SiH4)			
Option C:	Silicon oxide			
Option D:	Silicon dioxide			
Q3.	As the channel length is reduced in a MOS transistor, depletion region width must			
	be			
Option A:	Increased			
Option B:	Decreased			
Option C:	Must not vary			
Option D:	Exponentially decreased			
Q4.	The size of a transistor is usually defined in terms of its			
Option A:	Channel length			
Option B:	Feature size			
Option C:	Width			
Option D:	Thickness 'd'			
Q5.	Which gives scalable design rules?			
Option A:	Lambda rules			
Option B:	Micron rules			
Option C:	Layer rules			
Option D:	Thickness rules			
Q6.	What can be used for connecting Diffusion and polysilicon layers?			
Option A:	Butting contact			
Option B:	Buried contact			
Option C:	Separate contact			
Option D:	Cannot be connected			
Q7.	What is minimum feature size for thick oxide?			

### **Examination 2020 under cluster 4 (PCE)**

Option A:	2λ		
Option B:	3λ		
Option C:	4λ		
Option D:	λ		
1			
Q8.	The area of CMOS inverter is proportional to, which of the following?		
Option A:	Area of n device		
Option B:	Area of p device		
Option C:	Total area of n and p device		
Option D:	Square of minimum feature size		
1			
09.	The average power dissipated in resistive load n-MOS inverter is:		
Option A:			
Option B:	$V_{\rm DD} (V_{\rm DD} - V_{\rm OI})/R$		
Option C:	$\frac{1}{V_{\text{DD}}} \frac{1}{V_{\text{DD}}} \frac{1}{V_{DD}} \frac{1}{V_{DD}} \frac{1}{V_{DD}}} \frac{1}{V_{DD}} \frac{1}{V_$		
Option D:	$V_{DD} (V_{DD} - V_{H})/2R$		
option D.			
Q10. Option A: Option B:	$V_{DD}$ $A \leftarrow d = d = d = d = d = d = d = d = d = d$		
Option C:	OR gate		
Option D:	NOR gate		
	g		
011.	Zipper logic style is		
Option A:	Static CMOS		
Option B.	Dynamic CMOS logic		
Option C.	NOR A Logic style		
Option D.	$C^2$ MOS logic style		
Q12.	Advantages Dynamic CMOS Circuit over a Static CMOS Circuit		
Option A:	Transistors required are more		
Option B:	Transistors required are less		
Option C:	Clock is not required		
Option D.	Area required is more		
Spilon D.			

# University of Mumbai Examination 2020 under cluster 4 (PCE)

Q13.		
	For given circuit Z=?	
Option A:	$Z = BS + A\overline{S}$	
Option B:	$Z = AS + B\overline{S}$	
Option C:	Z = BS + AS	
Option D:	Z = AS + BS	
014		
Q14.	In clocked CMOS logic, rise time and fall time are	
Option A:	Faster	
Option B:	Slower Easter first and then aloung down	
Option C:	Faster first and then sneeds up	
Option D:		
015	Read operation in memory is carried out using	
Option A:	Sensor	
Option B:	Decoder	
Option C:	Amplifier	
Option D:	Sense amplifier	
1		
Q16.	A full CMOS SRAM cell has	
Option A:	8T	
Option B:	6T	
Option C:	4T	
Option D:	2T	
Q17.	1-bit DRAM is made of	
Option A:	I-Flip-Flop	
Option B:	1-Transistor and Capacitor	
Option C:	1-1 ransistor	
Option D:	1-Inverter	
018	In CMOS SRAM static power dissipation is low due to	
Option $A$	Moderate leakage current	
Option R:	Large leakage current	
Option C:	Small leakage current	
	I SIIIAII ICANAZO CUITCIIL	

# Examination 2020 under cluster 4 (PCE)

Q19.	What are carry generate combinations?			
Option A:	If all the input are same then a carry is generated			
Option B:	If all of the output are independent of the inputs			
Option C:	If all of the input are dependent on the output			
Option D:	If all of the output are dependent on the input			
Q20.	A D flip-flop is used in a 4-bit serial adder, why?			
Option A:	It is used to invert the input of the full adder			
Option B:	It is used to store the output of the full adder			
Option C:	It is used to store the carry output of the full adder			
Option D:	It is used to store the sum output of the full addeR			
<b>-</b>				
Q21.	Based on how binary information is entered or shifted out, shift registers are			
	classified into categories.			
Option A:	2			
Option B:	3			
Option C:	4			
Option D:	5			
1				
Q22.	What is meant by parallel load of a shift register?			
Option A:	All FFs are preset with data			
Option B:	Each FF is loaded with data, one at a time			
Option C:	Parallel shifting of data			
Option D:	All FFs are set with data			
1				
Q23.	Power supply variation in the clock distribution causes a			
Option A:	Jitter			
Option B:	Skew			
Option C:	Slack			
Option D:	ESD			
- F				
O24.	Setup time is the interval of data signal arrived the clock pulse			
Option A:	Exact tick of			
Option B:	Before			
Option C:	After			
Option D:	Delayed to			
option D.				
025	The delay for a gate to switch 50% of its final if source resistance of 10kohm with			
<b>Z</b> =0.	the total lumped capacitance for a wire is 11pF			
Option A:	242ns			
Option B:	76ns			
Option C	110ns			
Option D:	55ns			

#### **Examination 2020 under cluster 4 (PCE)**

Program: BE Electronics and Telecommunication Engineering Curriculum Scheme: Rev2012 Examination: Third Year Semester VI Course Code: \_\_ETC606\_\_ and Course Name: \_VLSI Design\_\_\_

Time: 1 hour

Max. Marks: 50


Question	Correct Option (Enter either 'A' or 'B' or 'C' or 'D')		
Q1.	С		
Q2.	В		
Q3.	В		
Q4	А		
Q5	А		
Q6	А		
Q7	В		
Q8.	С		
Q9.	С		
Q10.	В		
Q11.	В		
Q12.	В		
Q13.	В		
Q14.	В		
Q15.	D		
Q16.	В		
Q17.	В		
Q18.	С		
Q19.	В		
Q20.	С		
Q21.	С		
Q22.	В		
Q23.	А		
Q24.	В		
Q25.	В		